These assemblies are ESD sensitive. ESD precautions shall be observed.

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Shorting plug TP7 shall be raised to minimum height of 250mils above PCB.

Components marked 'DNP' should not be populated.

Assembly Variant: 001
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
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<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-00867</th>
<th>REV: A</th>
<th>SUN REV: Not In VersionControl</th>
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<td></td>
<td>TID #: N/A</td>
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| PLOT NAME = Bottom Assembly Drawing | GENERATED : 9/14/2015 3:19:30 PM | TEXAS INSTRUMENTS |
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